Shenzhen Jianghe New Materials Technology Co.,Ltd

Technical Data Sheet (TDS)

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Doc No.: EPR-2120A-C+2120B-M3-2-TDS-012
Issue Date: 2023-05-20
Revision: 1.0

2120A-C+2120B-M3-2

Typical Properties

Epoxy Resin 2120A-C+2120B-M3-2 is an environmentally compliant epoxy adhesive formulated to cure under both ambient and low-temperature conditions. It exhibits excellent leveling properties with self-debubbling capability, provides yellowing resistance, and achieves high optical clarity without surface distortion. The system produces a glossy finish and is suitable for either room temperature or thermally accelerated curing processes.

Applications

Epoxy Resin 2120A-C+2120B-M3-2 is specifically engineered for module potting, mold casting, and electronic component protection applications including insulation, moisture-proof encapsulation, and secure shielding.

Physical & Chemical Properties

Property	Part A: 2120A-C	Part B: 2120B-M3-2
Color	Light blue, transparent	Light blue, transparent
Density (g/cm³)	1.07±0.05	0.98±0.03
Viscosity (mPa•s)	2000±500	100±50
Brookfield DV2TRV Viscometer	25℃	
Mix Ratio (by Weight)	2 : 1	

Properties of Cured Material

Property	Base + Curing Agent
Physical State	Liquid
Viscosity (mPa•s)	500±200mPa.S
Brookfield DV2TRV Viscometer	25℃
Pot Life (100g mass @ 25°C)	30-40 min
Dosage	280-350 g/m² (varies with substrate)

Processing & Curing Parameters

Initial Cure (50G)	8-12 hours to surface dry at room temperature
Full Cure (50G)	24-36 hours at Room Temperature (RT)
Service Temperature Range	0℃ to 80℃

Application Instructions

Working Conditions: Ensure the mixing container is clean. Measure Components A and B strictly by the designated weight ratio. After accurate weighing, stir the mixture thoroughly in a clockwise direction, scraping the inner walls of the container. Allow the mixture to rest for 3-5 minutes before application.

Precautions

1. **Dosage Control:** Prepare the adhesive quantity based on the pot life and application rate to avoid waste.
2. **Low-Temperature Handling:** When the ambient temperature falls below 15°C, preheat Component A to 30°C before mixing to facilitate easier application, as the viscosity increases in cold conditions.
3. **Storage After Use:** The container must be sealed immediately after use to prevent moisture absorption, which can render the product unusable.
4. **High-Humidity Curing:** At relative humidity levels above 85%, the cured surface is prone to absorbing moisture from the air, forming a whitish haze. Therefore, room

temperature curing is not recommended under these conditions; heat-assisted curing is advised.

Test Result

Hardness	Shore D	82±2
Heat Deflection Temperature	℃	60
Water Absorption	%	<0.1

Save

Freeze-Sensitive	Yes	
Moisture-Sensitive	Resin	Curing Agent
	No	Sensitive
Recommended Storage Temperature	15℃ to 25℃ (Must not fall below 10℃ or exceed 50℃.)	
Shelf Life	6 months in original, unopened packaging	
Packaging	Resin	Curing Agent
	5 kg pail	5 kg pail

Note: The performance data provided above are typical values obtained under laboratory conditions of 25°C and 70% relative humidity. They are for reference purposes only.